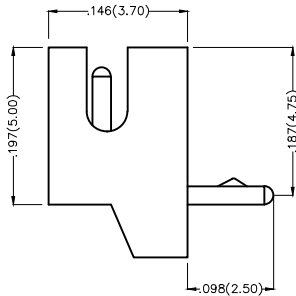
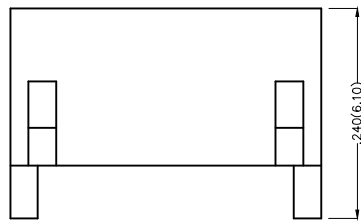
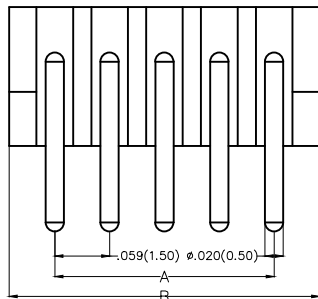


REV	LOCATIONS	DESCRIPTION	DATE	REVISER	APPD



Electrical
 Current Rating: 1.0A AC(rms)/DC
 Voltage Rating: 50V AC(rms)/DC
 Contact Resistance: 20 mΩ Max
 Insulation Resistance: 500 MΩ MIN
 Withstanding Voltage: 500V AC r.m.s
 Temperature Range—Operating: -25°C~+85°C

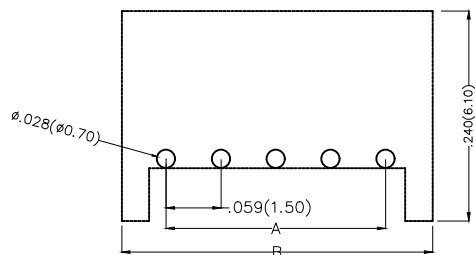
Material and Plating
 Housing: PA46(UL 94V-0)
 Contact Pin: Brass
 Plating: Tin Plated



Ordering Information

FWF 150 03 — S XX B 2 6 W5 B
 1 2 3 4 5 6 7 8 9 10

1 Category FWF—Wafer	2 Series Number 150—Pitch 1.5mm	3 Distinction No. 03	4 Row Option S—Single Row	5 Circuits XX	6 Entry Angle B—90° Angle
7 Plating 2—Tin Plated	8 Material—Resin 6—PA46	9 Color—Resin W5—White	10 Packaging B—PE Bag		





Recommended P.C.Board Layout

 THIRD ANGLE PROJECTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		APPROVE BY FRANK	DATE 8/JUL/13	PART NO. FWF15003-SXXB26W5B	ITEM NO. FWF15003	 Leader Of Industry
	DESIGN UNITS Inch (metric)	X.±.012(0.30) X.±5'	CHECKED BY JACOB	DATE 8/JUL/13	TITLE Wire to Board (Wafer) Pitch 1.5mm 90° Angle (DIP)		
SCALE 5:1	SIZE A4	X.XX±.006(0.15) .XX±1'	DRAWN BY CHERRY	DATE 8/JUL/13	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO TXGA INDUSTRIAL ELECTRONICS(S.Z)CO.,LTD AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		

REV	LOCATIONS	DESCRIPTION	DATE	REVISER	APPD

Circuits (n)	Part No.	Dimensions(in/mm)	
		A	B
2	FWF15003-S02B26W5B	.059(1.50)	.177(4.50)
3	FWF15003-S03B26W5B	.118(3.00)	.236(6.00)
4	FWF15003-S04B26W5B	.177(4.50)	.295(7.50)
5	FWF15003-S05B26W5B	.236(6.00)	.354(9.00)
6	FWF15003-S06B26W5B	.295(7.50)	.413(10.50)
7	FWF15003-S07B26W5B	.354(9.00)	.472(12.00)
8	FWF15003-S08B26W5B	.413(10.50)	.531(13.50)
9	FWF15003-S09B26W5B	.472(12.00)	.591(15.00)
10	FWF15003-S10B26W5B	.531(13.50)	.650(16.50)
11	FWF15003-S11B26W5B	.591(15.00)	.709(18.00)
12	FWF15003-S12B26W5B	.650(16.50)	.768(19.50)

 THIRD ANGLE PROJECTION	GENERAL TOLERANCES (UNLESS SPECIFIED)		APPROVE BY FRANK	DATE 8/JUL/13	PART NO. FWF15003-SXXB26W5B	ITEM NO. FWF15003	 Leader Of Industry	
	DESIGN UNITS Inch (metric)	X.±.012(0.30)	X.±5°	CHECKED BY JACOB	DATE 8/JUL/13	TITLE Wire to Board (Wafer) Pitch 1.5mm 90° Angle (DIP)		REV 0
SCALE 5:1	SIZE A4	X.XX±.006(0.15)	X.XX±1°	DRAWN BY CHERRY	DATE 8/JUL/13	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO TXGA INDUSTRIAL ELECTRONICS(S.Z)CO.,LTD AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		
		X.XXX±.004(0.10)	.XXX±0.5°					